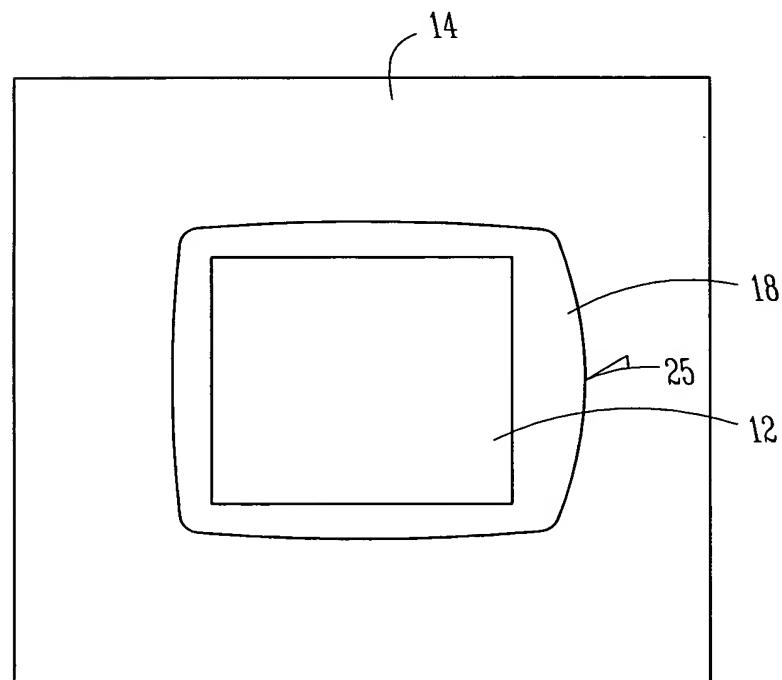


*Fig. 1A (Prior Art)*



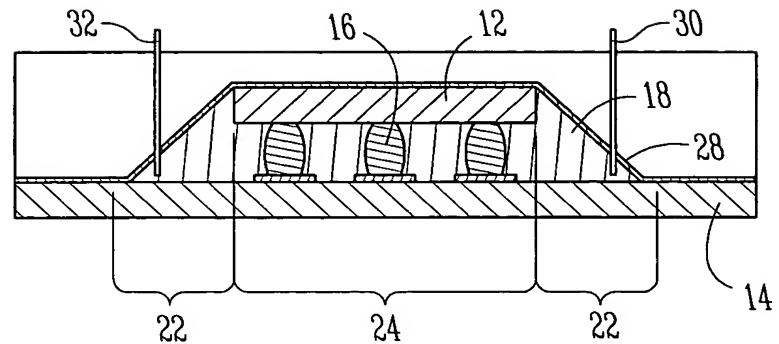
*Fig. 1B (Prior Art)*

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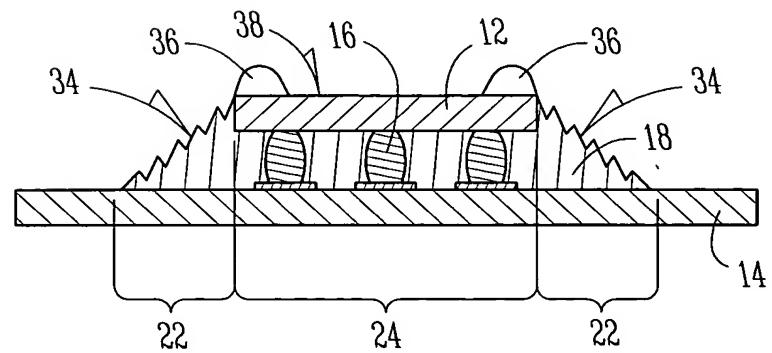
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*Fig. 2A (Prior Art)*



*Fig. 2B (Prior Art)*

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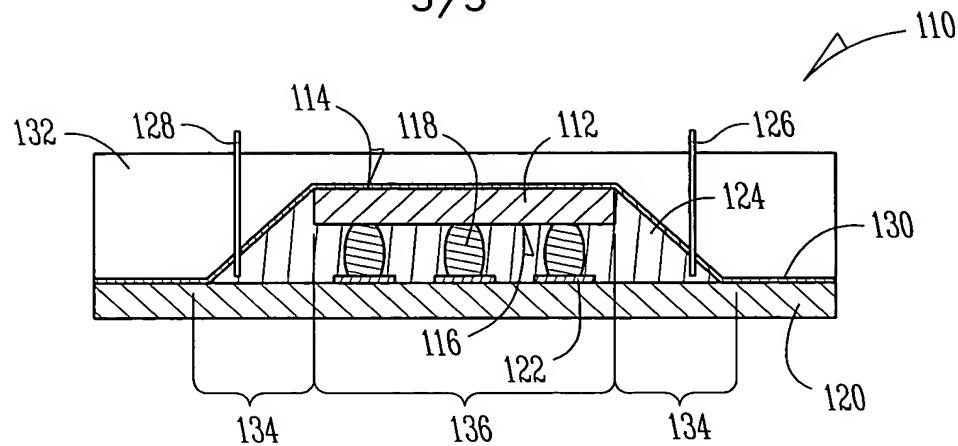


Fig. 3A

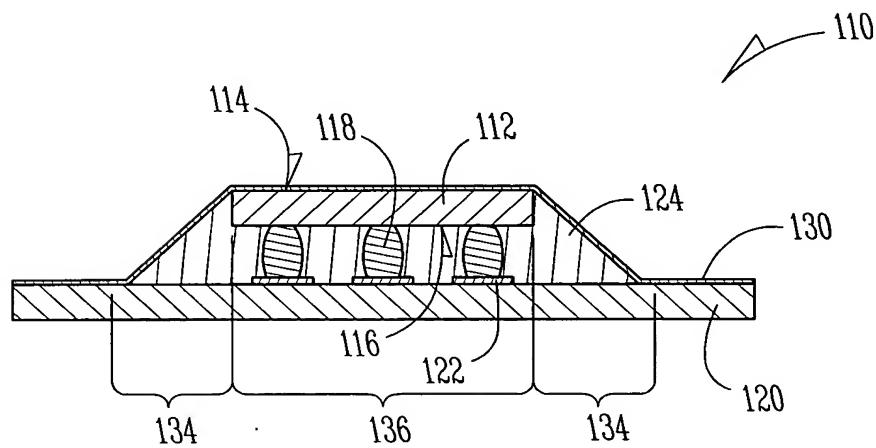


Fig. 3B

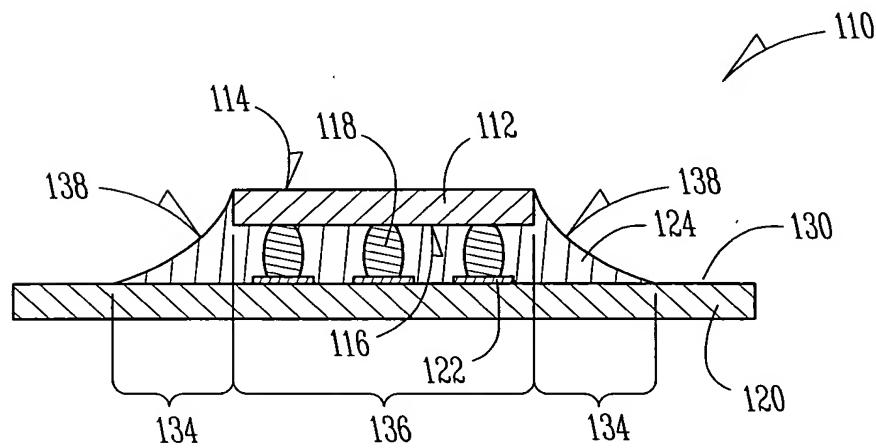
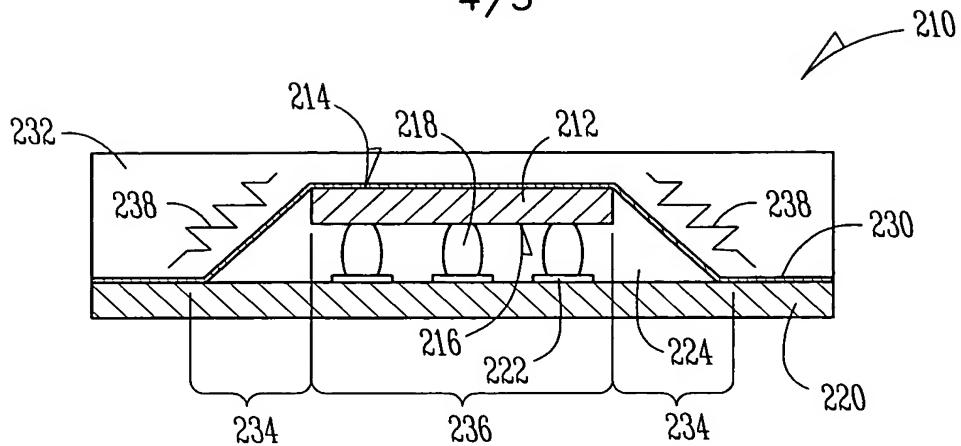
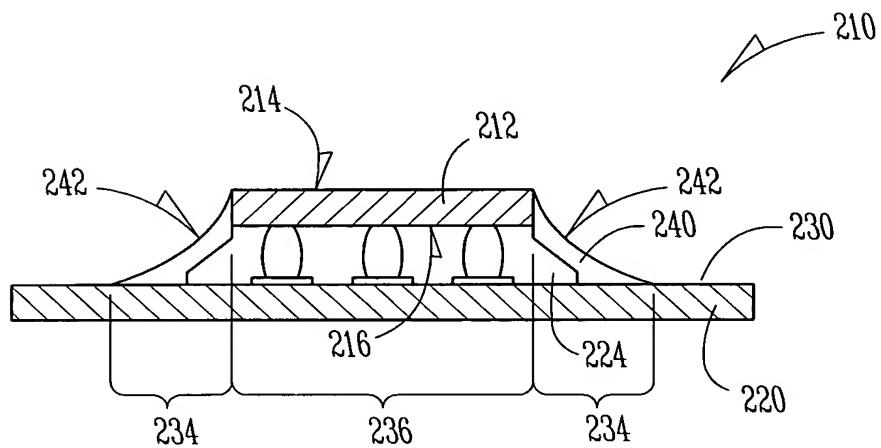


Fig. 3C

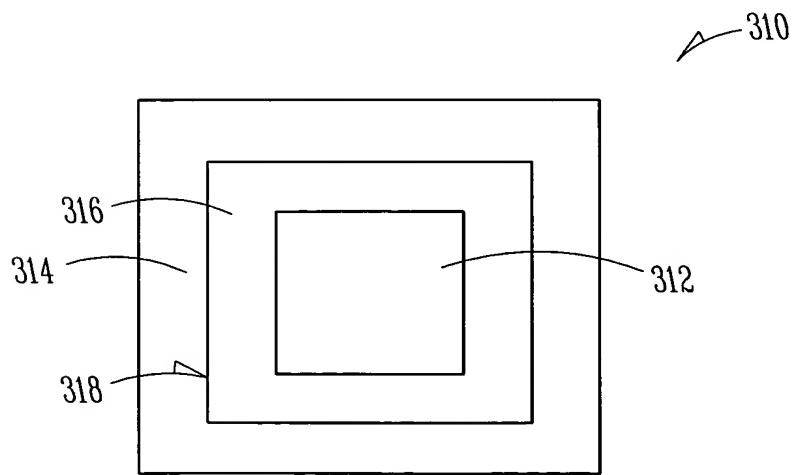
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*Fig. 4A*



*Fig. 4B*



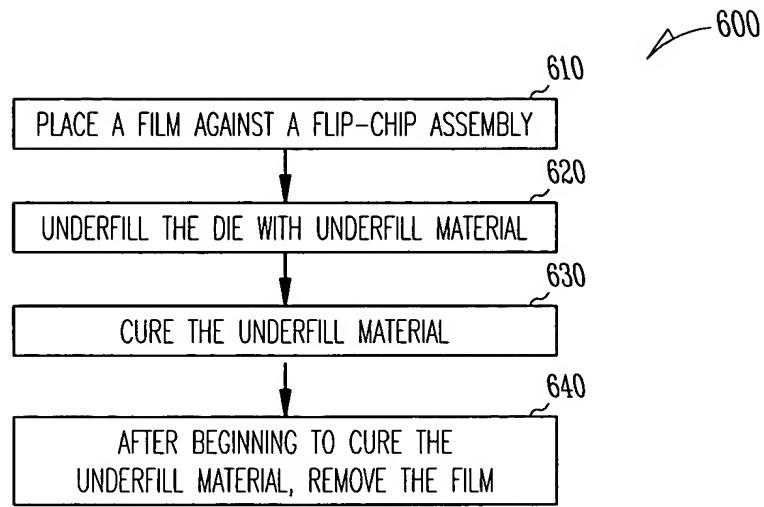
*Fig. 5*

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*Fig. 6*